



## **PRESS RELEASE**

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### **TechSearch International's Analysis Shows Surge in Fan-Out and Embedded Bridge for High Performance Packaging**

With AMD's announcement of its Elevated Fanout Bridge (EFB) GPU package, the embedded bridge for fan-out (FO) on substrate is in the spotlight. With assembly of EFB at an OSAT, the development highlights the ability of OSATs to have a strong play in the high-performance packaging market. TechSearch International discusses the advantages of fan-out on substrate and embedded bridge structures with an emphasis on packaging for advanced nodes in its latest *Advanced Packaging Update (APU)*. The adoption of chiplets is expected to remain one of the most important advances in this decade. Advanced packaging options from foundries, IDMs, and OSATs are highlighted including developments in 3D. Challenges such as test and thermal issues are presented with some potential solutions. A market forecast for silicon interposer and high-density FO packages is provided. Trends in high bandwidth memory (HBM) are discussed and a market forecast is included.

Continuing semiconductor shortages and supply chain disruptions are discussed. OSAT financials for the first half of the year are analyzed. TechSearch International quantifies the gap between manufacturing demand and capacity and shows it will continue through 2025. The report discusses how the gap could be reduced with higher yields for large substrates.

The latest APU is a 43-page report with full references and an accompanying set of more than 50 PowerPoint slides.

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